Präz. Buchsenleiste - RM 2,54 mm - 1-/2-reihig

Precision Female Header - Pitch 2,54 mm - Single and Double Row

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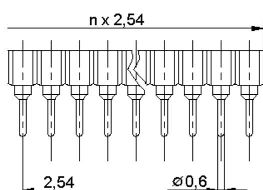
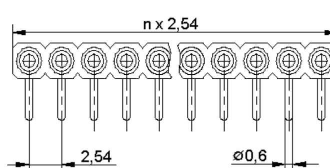
Technische Daten / *Technical Data*:

Isolierkörper	Thermoplastischer Kunststoff, nach UL94V0
Insulator	*Thermoplastic, rated UL94V0*
Kontaktmaterial	Hülse: Messing gedreht Feder: 6 Lamellen-Clip, Beryllium-Kupfer
Contact Material	*Sleeve: Screw Machined Brass* *Clip: 6 Finger-Clip, Beryllium-Copper*
Kontaktoberfläche	lt. Oberflächenoptionen, über Ni (1,3-2,5 µm)
Contact Surface	*acc. to options (see below), over Ni (1,3-2,5 µm)*
Lötbarkeit	IEC512-12A
Solderability	*IEC512-12A*
Durchgangswiderstand	≤ 10 mOhm
Contact Resistance	*≤ 10 mOhm*
Isolationswiderstand	> 10^{10} Ohm
Insulation Resistance	*> 10^{10} Ohm*
Spannungsfestigkeit	1000 V_{RMS}
Test Voltage	*1000 V_{RMS}*
Nennstrom	3 A
Current Rating	*3 A*
Temperaturbereich	-55°C...+125°C
Temperature Range	*-55°C...+125°C*
Verarbeitung	Reflow-Lötverfahren; weitere Informationen in Kapitel T
Processing	*Reflow-Soldering, further informations in chapter T*

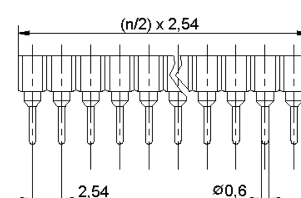
Single Row - Straight



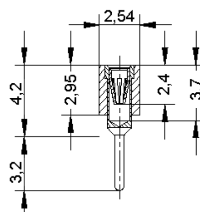
Single Row - Right Angled

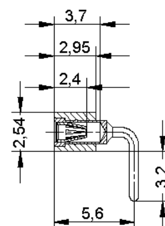


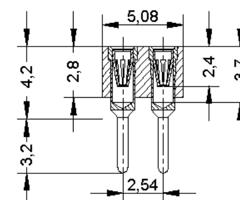
Double Row - Straight



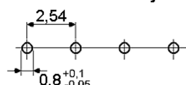
n = Anzahl Kontakte
n = No. of Contacts



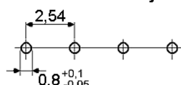




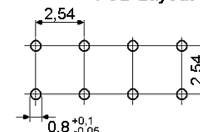
PCB-Layout



PCB-Layout



PCB-Layout



Series	***Contacts****	***Type****	***Sleeve Plating***	***Clip Plating****
254	01	2	50	30
	01-64-pol. einreihig *single row* **04-72**-pol. zweireihig *double row*	**1** = einreihig, gerade *single row, straight* **2** = einreihig, gewinkelt *single row, right angled* **3** = zweireihig, gerade *double row, straight*	**50** = Hülse verzinnt *sleeve tin plated*	**10** = Feder 0,25 µm Gold *0,25 µm gold plated* **30** = Feder 0,75 µm Gold *0,75 µm gold plated*

(* Bestellbeispiel - Bitte durch Ihre Spezifikationen ersetzen.
** Order example - To be replaced by your specifications.*)

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Informationen zum Reflow-Lötverfahren

Reflow-Soldering Informations

Reflow-Lötverfahren

Reflow-Soldering

Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflowverfahren verarbeitet werden (Maximalwerte):

Profil Eigenschaft	Bleifreies Löten
Durchschnitts-Ramp-Up Rate (Ts_{max} to Tp)	3 °C / Sek. Max.
Vorheizen - Temperatur Min (Ts_{min}) - Temperatur Max (Ts_{max}) - Zeit (ts_{min} auf ts_{max})	 150°C 200°C 60-180 Sekunden
Verbleiben oberhalb: - Temperatur (T_L) - Zeit (t_L)	 217°C 60-150 Sekunden
Peak/Klassifizierung Temperatur (Tp)	260°C +/- 5°C
Zeit innerhalb von 5°C um die Peak-Temperatur (tp)	20-40 Sekunden
Ramp-Down Rate	6°C / Sekunde max.
Zeit von 25°C bis zur Peak-Temperatur	8 Minuten max.

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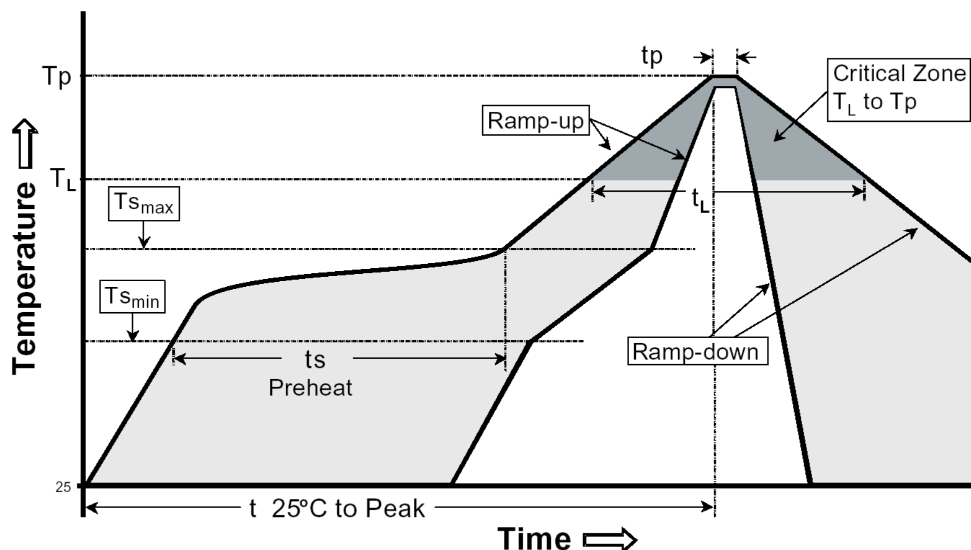
Items should be soldered according to IPC/JEDEC J-STD-020C temperature-profile for leadfree reflow-soldering (maximum values):

Profile Feature	PB-Free assembly
Average Ramp-Up Rate (Ts_{max} to Tp)	3 °C / second max.
Preheat - Temperature Min (Ts_{min}) - Temperature Max (Ts_{max}) - Time (ts_{min} to ts_{max})	 150°C 200°C 60-180 seconds
Time maintained above: - Temperature (T_L) - Time (t_L)	 217°C 60-150 seconds
Peak/Classification Temperature (Tp)	260°C +/- 5°C
Time within 5°C of actual Peak Temperature (tp)	20-40 seconds
Ramp-Down Rate	6°C / second max.
Time 25°C to Peak Temperature	8 minutes max.

Empfohlenes Reflow-Lötprofil:

Recommended Reflow-Soldering profile:



T